## DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled

# METHOD AND APPARATUS FOR ADJUSTING THE THICKNESS OF A LAYER OF SEMICONDUCTOR MATERIAL

and for which a patent application:  is attached hereto and includes a	nmendment(s) filed on		(if ap	plicable)	
was filed in the United States or	n as Application N	No.	6	declaration not	
accompanying application) with was filed as PCT international A	amendment(s) filed on		(	if applicable)	
under PCT Article 10 on	Application No.	on	and	was amended	
under FC1 Article 19 on			(if applicable)		
I hereby state that I have reviewe amended by any amendment referre	ed and understand the conted to above.	ents of the above identified ap	plication, includin	g the claims, as	
I acknowledge the duty to disclose Regulations, § 1.56.	information known to me to	be material to patentability as d	efined in Title 37,	Code of Federal	
I hereby claim foreign priority bene inventor's certificate listed below as a filing date before that of the appli	nd have also identified belo	w any foreign application for pa	foreign application tent or inventor's c	n(s) for patent or ertificate having	
EARLIEST FOREIGN APPLI	CATION(S), IF ANY, FILE	ED PRIOR TO THE FILING DA	TE OF THE APP	LICATION	
APPLICATION NUMBER	COUNTRY	UNTRY DATE OF FILING (day, month, year) PRIORITY		CLAIMED	
0210208	France	August 12, 2002	⊠ YES	□ NO	
0210209	France	August 12, 2002	⊠ YES	□ NO	
I hereby claim the benefit under 1 below.	Γitle 35, United States Cod	le, § 119(e) of any United State	es provisional app	lication(s) listed	
PROVISIONAL APPLIC	ATION NUMBER	FILING DATE			

NON-PROVISIONAL APPLICATION NO.		FILING DATE	STATUS			
		TIEMO DATE	PATENTED	PENDING	DING ABANDONED	
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me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between

the filing date of the prior application and the national or PCT international filing date of this application:

<sup>\*</sup> for use only when the application is assigned to a company, partnership or other organization.

1.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

-	T	LAST NAME	FIRST NAME	MIDDLE NAME		
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L		<u> </u>	*******************************			



#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Bruno GHYSELEN et al.

Application No.:

Group Art Unit:

Filing Date:

August 6, 2003

Examiner:

For:

METHOD AND APPARATUS FOR ADJUSTING THE THICKNESS

Attorney Docket No.: 4717-6300

OF A LAYER OF SEMICONDUCTOR MATERIAL

### POWER OF ATTORNEY BY ASSIGNEE AND EXCLUSION OF INVENTOR(S) UNDER 37 C.F.R. 3.71

Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

The undersigned assignee of the entire interest in the above-identified subject application hereby appoints Allan A. Fanucci (Reg. No. 30,256) and Daniel J. Hulseberg (Reg. No. 36,554) of WINSTON & STRAWN (Customer No. 28765) to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith.

Please direct all correspondence for this application to Customer No. 28765 to the attention of Allan A. Fanucci (telephone 212-294-3311, facsimile 212-294-4700).

An assignment of the entire interest in the above-identified subject application is submitted herewith for recording and a copy is attached. The undersigned has reviewed this assignment and, to the best of his knowledge, title is in the assignee seeking to take action in this application and that he is empowered to act on its behalf.

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#### S.O.I. TEC SILICON ON INSULATOR TECHNOLOGIES S.A.

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